



3D SOLDER
PASTE INSPECTION

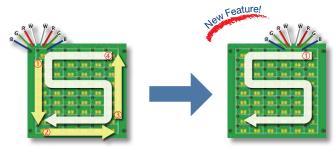
TR7007 SII Plus FFATURES

TR7007 SII Plus

Highly Accurate shadow-free SPI solution with class-leading inspection performance and easy programming brings maximum value to your production line.

Unmatched Speed & Throughput

Industry-leading inspection speed using TRI's Dynamic Imaging technology keeps up with the production line beat without slowing down for even the most complex boards with multiple local fiducial marks. TRI's unique solution guarantees perfect results while reducing expensive cycle time.



TRI's Color Imaging needs to scan only one Fiducial Mark on every board, saving cycle time.

Stable and Reliable Performance

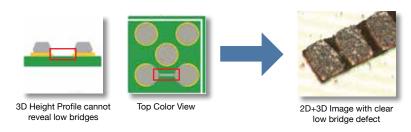
Fully optimized for maximum stability, the TR7007 SII Plus delivers reliable inspection results 24 hours a day, and automatically compensates for manufacturing tolerances and board warp.



Reliable warp compensation and local fiducial marks guarantee stable results under any conditions.

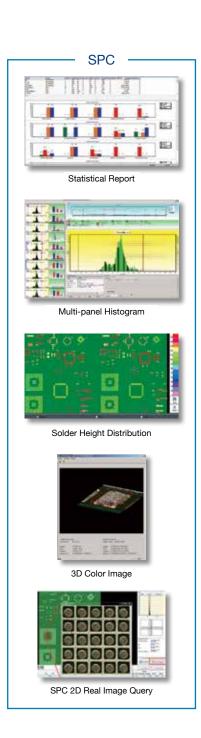
Unique Low Bridge Inspection

World's first inspection of low solder paste bridges under 30 µm ensures no printing defects are missed, and guarantees accurate results under any conditions.



Intuitive SPC Display

Full panel maps and real color images allow engineers to quickly monitor and diagnose problematic areas on the stencil, saving management time and reducing rework costs.



Intelligent Easy Programming Interface

Rapid intelligent 5-step programming interface ensures fast changeovers, minimal idle time and helps reduce operator work load.



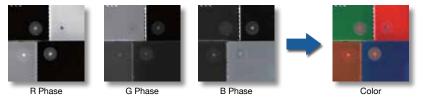
Shadow Free Inspection Technology

Dual projection design and intelligent software ensure the TR7007 SII Plus delivers completely shadow-free inspection results and eliminates problems with specular reflections.



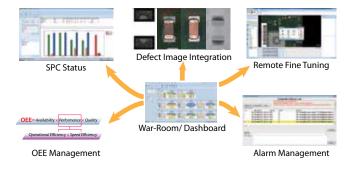
Multi-Color Vision for any PCB

Multi-phase color lighting guarantees accurate inspection results on any PCB color and finish combination, without sacrificing inspection speed.



Yield Management System 4.0

YMS 4.0 provides real-time inspection status across SPI, AOI and AXI systems and monitors SPC and Alarm status, and supports remote fine-tune throughout the SMT line. The centralized inspection management provides top 5 to 10 defects and defective images, OEE review and management, issue and root cause drill down line by line, by station and by process, which improves quality and productivity analysis. YMS 4.0 supports Industry 4.0 initiative.



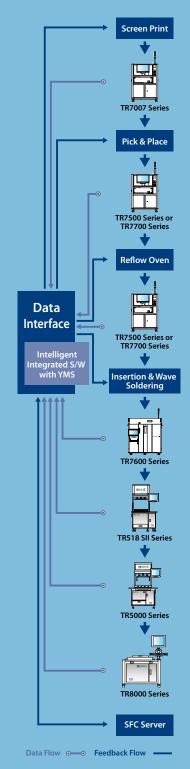
Closed Loop Function

TRI SPI systems share inspection results with connected SMT line equipment to help improve production yields and stabilize production quality while minimizing line stops and reducing production costs.

High Production Value = Maximum Cost Savings

- Industry Leading Inspection Speed
- Early Defect Detection
- 98% Rework Cost Reduction
- Stable and Reliable Results
- Enhanced 100% Defect Coverage

Yield Management System*



- Inspection results and data integration
- Real time SPC and production yield management
- Quality reports and closed loop tracking
- Support defect component analysis and improvements
- Knowledge Management (KM)
- Productivity and Quality Management
 - * Options

PECIFICATIONS

Optical &	Imaging	System
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Camera Type	4 Mpx camera	
Optical Resolution	10 μm or 15 μm (factory setting)	
Field of View	10 μm	20.0 x 20.0 mm (0.79 x 0.79 in)
	15 µm	30.0 x 30.0 mm (1.18 x 1.18 in)

Inspection Functions

Defects Detected	Insufficient Paste, Excessive Paste, Shape Deformity, Missing Paste & Bridging
Measurement	Height, area, volume and offset
Machanical Stage	

Mechanical Stage

X-axis linear motor and linear scale with DSP-based motion controller

XY Resolution	0.5 µm
Z Resolution	1 µm
Inspection Speed	

Inspection Speed

10 μm	Up to 90 cm ² /sec
15 µm	Up to 200 cm ² /sec

Inspection Performance

Volume Repeatability	Calibration Target (at 3σ)	<1% on TRI calibration target
Height Repeatability	Calibration Target (at 3σ) Solder GR&R (± 50% Tolerance)	<1% on TRI calibration target <<10% at 6 σ
Height Resolution	0.4 μm	
Height Accuracy	1.5 µm on calibration target	<u> </u>
Max. Solder Paste Size	12800 x 10240 µm at 10 µm	7 7
Min. Solder Paste Size	100 x 100 μm at 10 μm	
Min. Solder Paste Pitch	100 μm	
Max. Height Range	10 μm 600 μm	



15 μm 550 μm

PCB and Conveyor System

Min. PCB Size	50 x 50 mm (1.97 x 1.97 in.)			
Max. PCB Size	TR7007M SII Plus	TR7007 SII Plus	TR7007L SII Plus	
	350 x 350 mm (13.8 x 13.8 in.)	510 x 460 mm (20.1 x 18.1 in.)	660 x 610 mm (26.0 x 24.0 in.)	
	TR7007 SII Plus DL			
	510 x 310 mm x 2 lanes (20.1 x 12.2 in. x 2 lanes) 510 x 590 mm x 1 lane (20.1 x 23.2 in. x 1 lane)			
PCB Thickness	0.6 - 5 mm			
PCB Transport Height	880 - 920 mm (34.6 - 36.2 in.)			
Max. PCB Weight	3 kg (6.61 lbs)			
PCB Carrier/Fixing	Belt/Pneumatic			
Clearance Top Bottom Edge	25 mm (0.98 in.) 40 mm (1.58 in.) 3 mm (0.12 in.)			
Dimensions	TR7007M SII Plus	TR7007 SII Plus	TR7007L SII Plus	
Dimensions (W x D x H) /Weight	1000 x 1555 x 1500 mm (39.4 x 61.2 x 59.1 in.) (not including signal tower, height: 520 mm)	1100 x 1570 x 1550 mm (43.3 x 61.8 x 61.0 in.) (not including signal tower, height: 520 mm)	1300 x 1610 x 1560 mm (51.2 x 63.4 x 61.4 in.) (not including signal tower, height: 520 mm)	
	870 kg (1918 lbs)	950 kg (2094 lbs)	1250 kg (2756 lbs)	
	TR7007 SII Plus DL			
	1100 x 1770 x 1560 mm (43.3 x 65.7 x 61.0 in.) (not including signal tower, height: 520 mm)			
	1100 kg (2425 lbs)			
Power Requirement	200 - 240 V, single phase, 50/60 Hz 3 kVA			
Air Requirement	72 psi – 87 psi (5 – 6 Bar)			

SPC, Offline Editor, Gerber Tool, Barcode Scanner (linear & 2D) and Support Pins, Closed Loop Function, Dual Lane, Y-Axis Linear Motor, TRI's Yield Management System (YMS 4.0), YMS Lite

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